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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	36
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	40-UFQFN Exposed Pad
Supplier Device Package	40-UQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1517-i-mv

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2.0 DEVICE PINOUTS

The pin diagrams for the PIC16(L)F151X/152X family are shown in Figure 2-1 through Figure 2-7. The pins that are required for programming are listed in Table 1-1 and shown in bold lettering in the pin diagrams.

FIGURE 2-1: 28-PIN SPDIP, SOIC, SSOP DIAGRAM FOR PIC16(L)F1512, PIC16(L)F1513, PIC16(L)F1516 AND PIC16(L)F1518

SPDIP, SOIC, SSOP		
	\bigcirc	28 _ ← ► RB7/ICSPDAT
RA0 🛶 🗖 🛛		
RA1 🛶 🗖 🕄	}	26 - → RB5
RA2 🛶	ļ	25 _ ←► RB4
RA3 🛶 🔤		24 → RB3
RA4 🛶	512 513 516 518 518	23 → RB2
RA5 🔸 🗌 7	ĔĔĔĔ	22 - → RB1
Vss →		, 21 _ ← → RB0
RA7 🔫 🗕	ូ ភូភូភូភូ	
RA6		19 −−− V ss
RC0 -	1	18 - RC7
RC1 -	2	17 ← ► RC6
RC2 → 1	3	16 → RC5
RC3 ◄ ► []1	4	15 - - - - - - - - - -

FIGURE 2-2: 28-PIN UQFN DIAGRAM FOR PIC16(L)F1512, PIC16(L)F1513, PIC16(L)F1516 AND PIC16(L)F1518

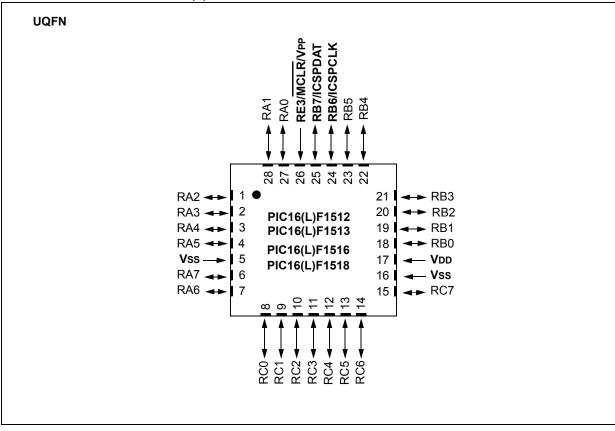
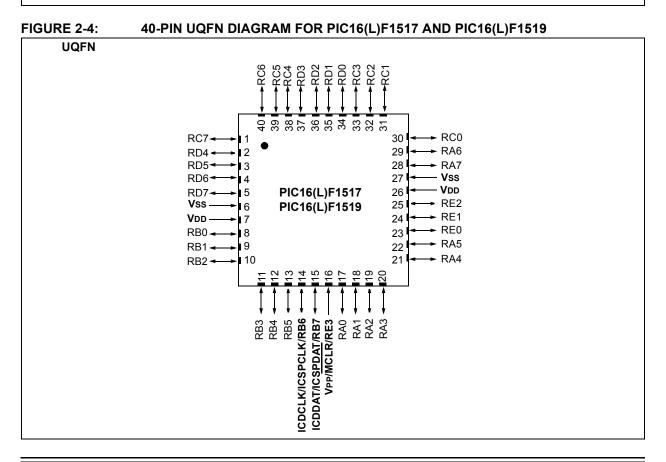


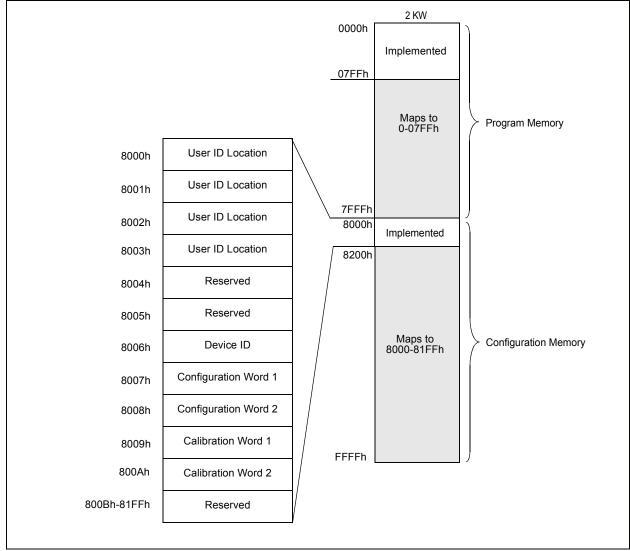
FIGURE 2-3:	40-PIN PDIP DIAGRAM F	OR PIC1	6(L)F1517 AND PIC16(L)F1519
PDIP			
	Vpp/MCLR/RE3 1	\bigcirc	40 RB7/ICSPDAT/ICDDAT
	RA0 🔶 2		
	RA1 🗕 🗕 🔤 3		38 → RB5
	RA2 🛶 🗖 4		37 → RB4
	RA3 🛶 🗖 5		36 → RB3
	RA4 🖛 🛏 6		35 🗌 🗲 → RB2
	RA5 🔶 7		34 → RB1
	RE0 🗕 🕨 🔤 8	<u>⊳</u> 6	33 - → RB0
	RE1 🛶 🕨 🗍 9	151	32 - VDD
	RE2	PIC16(L)F1517 PIC16(L)F1519	31
	V DD —— 11	:16(:16(30 - → RD7
	Vss —► 12		29 🗌 🖛 🕨 RD6
	RA7 🛶 🗖 13		28 🗌 🔸 RD5
	RA6 💶 14		27 🗌 🖛 → RD4
	RC0 🔶 🚺 15		26 - → RC7
	RC1 🗕 🗕 16		25 🗌 🛶 RC6
	RC2 🗕 ► 🗌 17		24 🗌 🛶 RC5
	RC3 🗕 ► 🗌 18		23 🗌 🖛 RC4
	RD0 🗕 ► 🗌 19		22 - → RD3
	RD1 ← ► 20		21 RD2

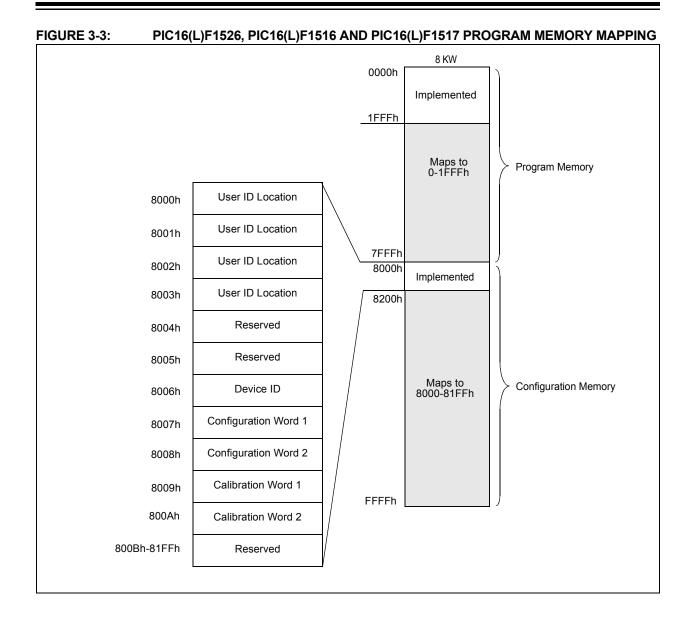


3.0 MEMORY MAP

The memory for the PIC16(L)F151X/152X devices is broken into two sections: program memory and configuration memory. Only the size of the program memory changes between devices, the configuration memory remains the same.







	DEVICE	ID VALUES
DEVICE	DEV	REV
PIC16F1527	0001 0101 101	x xxxx
PIC16F1526	0001 0101 100	x xxxx
PIC16LF1527	0001 0101 111	x xxxx
PIC16LF1526	0001 0101 110	x xxxx
PIC16F1519	0001 0110 111	x xxxx
PIC16F1518	0001 0110 110	x xxxx
PIC16F1517	0001 0110 101	x xxxx
PIC16F1516	0001 0110 100	x xxxx
PIC16F1513	0001 0110 010	x xxxx
PIC16F1512	0001 0111 000	x xxxx
PIC16LF1519	0001 0111 111	x xxxx
PIC16LF1518	0001 0111 110	x xxxx
PIC16LF1517	0001 0111 101	x xxxx
PIC16LF1516	0001 0111 100	x xxxx
PIC16LF1513	0001 0111 010	X XXXX
PIC16LF1512	0001 0111 001	X XXXX

TABLE 3-1: DEVICE ID VALUES

3.3 Configuration Words

There are two Configuration Words, Configuration Word 1 (8007h) and Configuration Word 2 (8008h). The individual bits within these Configuration Words are used to enable or disable device functions such as the Brown-out Reset, code protection and Power-up Timer.

3.4 Calibration Words

The internal calibration values are factory calibrated and stored in Calibration Words 1 and 2 (8009h, 800Ah).

The Calibration Words do not participate in erase operations. The device can be erased without affecting the Calibration Words.

REGISTER 3-2: CONFIGURATION WORD 1

		R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
		FCMEN	IESO	CLKOUTEN	BORE	EN<1:0>	_
		bit 13			•		bit 8
R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
CP	MCLRE	PWRTE	WD ⁻	ΓE<1:0>		FOSC<2:0>	
bit 7							bit
Legend:							
R = Readable bit		P = Programmat	DIE DIT		nted bit, read as '		
0' = Bit is cleared	1	'1' = Bit is set		-n = value whe	n blank or after E	SUIK Erase	
bit 13	1 = Fail-Safe Clo	afe Clock Monitor E ock Monitor is enal ock Monitor is disa	bled				
bit 12	1 = Internal/Exte	external Switchover ernal Switchover m ernal Switchover m	ode is enabled				
bit 11	1 = CLKOUT fu	ock Out Enable bit unction is disabled unction is enabled	I/O or oscillato	r function on CLKO	UT pin.		
bit 10-9	11 = BOR enabl 10 = BOR enabl	ed during operatio olled by SBOREN	n and disabled i	•			
bit 8	Unimplemented: Read as '1'						
bit 7		ction bit ⁽²⁾ mory code protect mory code protect					
bit 6	$\frac{\text{If LVP bit} = 1}{\text{This bit is ig}}$ $\frac{\text{If LVP bit} = 0}{1 = \text{MCLR}}$	VPP pin function is	MCLR; Weak pul	I-up enabled. R internally disabled	t Weak pull-up un	ider control of WPL	A register
bit 5		-up Timer Enable b abled			,		
bit 4-3	WDTE<1:0>: Wa 11 = WDT enab 10 = WDT enab	atchdog Timer Ena bled bled while running rolled by the SWD	and disabled in				
bit 2-0	FOSC<2:0>: Os 111 = ECH: Ex 110 = ECM: Ex 101 = ECL: Ex 100 = INTOSC 011 = EXTRC 010 = HS oscil 001 = XT oscil	cillator Selection b kternal Clock, High xternal Clock, Med (ternal Clock, Low- c oscillator: I/O fund oscillator: RC fund	-Power mode: c ium-Power mode Power mode: or ction on OSC1 p tion on OSC1 p crystal/resonato nator on OSC2 p	e: on CLKIN pin n CLKIN pin bin in r on OSC2 pin and bin and OSC1 pin	OSC1 pin		
	-		-	le Power-up Timer. de protection is turr	ned off.		

		R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
		LVP	DEBUG	LPBOR	BORV	STVREN	_
		bit 13					bit
U-1	U-1	U-1	R/P-1	U-1	U-1	R/P-1	R/P-1
_	_	_	VCAPEN ⁽²⁾	_	_	WRT<	1:0>
bit 7					I	I	bit
Legend:							
R = Readable bit	t	P = Programma	ble bit	U = Unimpleme	nted bit, read as '1		
0' = Bit is cleared	t	'1' = Bit is set		-n = Value whe	n blank or after B	ulk Erase	
bit 13	LVP: Low-Volta	age Programming	Enable bit ⁽¹⁾				
		e programming e					
		LR/VPP must be u	1 0	ning			
bit 12		rcuit Debugger Mo					
)ebugger disabled)ebugger enabled		•		•	
bit 11	LPBOR: Low-F		,			-990	
2.1		r BOR is disabled					
	0 = Low-Power	r BOR is enabled					
bit 10		out Reset Voltage					
	 = Brown-out Reset voltage (VBOR), low trip point selected = Brown-out Reset voltage (VBOR), high trip point selected 						
h# 0		U	<i>/</i> 0 1 1				
bit 9		k Overflow/Under flow or Underflow					
	 Stack Overflow or Underflow will cause a Reset Stack Overflow or Underflow will not cause a Reset 						
bit 8-5	Unimplemented: Read as '1'						
bit 4	VCAPEN: Volta	age Regulator Ca	pacitor Enable bi	ts ⁽¹⁾			
	0 = VCAP funct	ionality is enabled	d on VCAP pin				
	1 = All VCAP pi	n functions are di	sabled				
bit 3-2	Unimplemente	ed: Read as '1'					
bit 1-0	WRT<1:0>: Flash Memory Self-Write Protection bits 2 kW Flash memory (PIC16(L)F1512):						
		ite protection off	<u>1512)</u> :				
		0h to 1FFh write-p	protected, 200h to	o 7FFh may be m	nodified by PMCC	N control	
	01 = 000	0h to FFFh write-	protected, 400h to	o 7FFh may be m	nodified by PMCC	N control	
		Oh to 7FFh write-		resses may be n	nodified by PMCC	ON control	
		emory (PIC16(L)F ite protection off	<u>1513)</u> .				
		0h to 1FFh write-p	protected, 200h to	o FFFh may be m	nodified by PMCC	N control	
		0h to 7FFh write-p	,	,	,		
		Dh to FFFh write-p mory (PIC16F/LF		•	nodified by PMCO	N control	
		ite protection off	1310/1317/1320	1.			
	10 = 000	0h to 1FFh write-p					
		Oh to FFFh write-					
		0h to 1FFFh write emory (PIC16F/L	•		modified by PINC	ON control	
		ite protection off		<u></u> .			
	10 = 000	0h to 1FFh write-p					
	01 - 000				a madified by DN	ICON control	
		0h to 1FFFh write 0h to 3FFFh write					

REGISTER 3-3: CONFIGURATION WORD 2

2: Applies to PIC16F151X/152X devices only. On PIC16LF151X/152X, the VCAPEN bit is unimplemented.

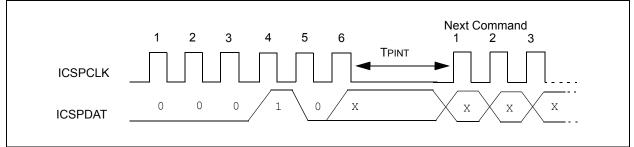
4.3.6 BEGIN INTERNALLY TIMED PROGRAMMING

A Load Configuration or Load Data for Program Memory command must be given before every Begin Programming command. Programming of the addressed memory will begin after this command is received. An internal timing mechanism executes the write. The user must allow for the program cycle time, TPINT, for the programming to complete.

The End Externally Timed Programming command is not needed when the Begin Internally Timed Programming is used to start the programming.

The program memory address that is being programmed is not erased prior to being programmed.



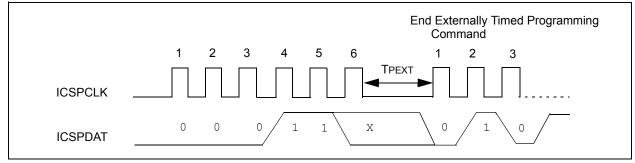


4.3.7 BEGIN EXTERNALLY TIMED PROGRAMMING

A Load Configuration or Load Data for Program Memory command must be given before every Begin Programming command. Programming of the addressed memory will begin after this command is received. To complete the programming the End Externally Timed Programming command must be sent in the specified time window defined by TPEXT (see Figure 4-7).

Externally timed writes are not supported for Configuration and Calibration bits. Any externally timed write to the Configuration or Calibration Word will have no effect on the targeted word.

FIGURE 4-7: BEGIN EXTERNALLY TIMED PROGRAMMING

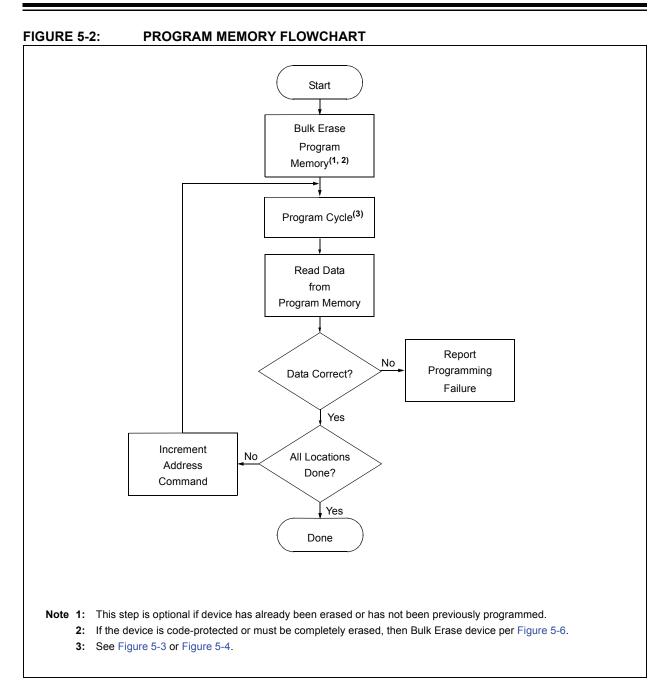


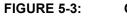
5.0 PROGRAMMING ALGORITHMS

The devices use internal latches to temporarily store the 14-bit words used for programming. Refer to Table 4-2 for specific latch information. The data latches allow the user to write the program words with a single Begin Externally Timed Programming or Begin Internally Timed Programming command. The Load Program Data or the Load Configuration command is used to load a single data latch. The data latch will hold the data until the Begin Externally Timed Programming or Begin Internally Timed Programming or Begin Internally Timed Programming command is given.

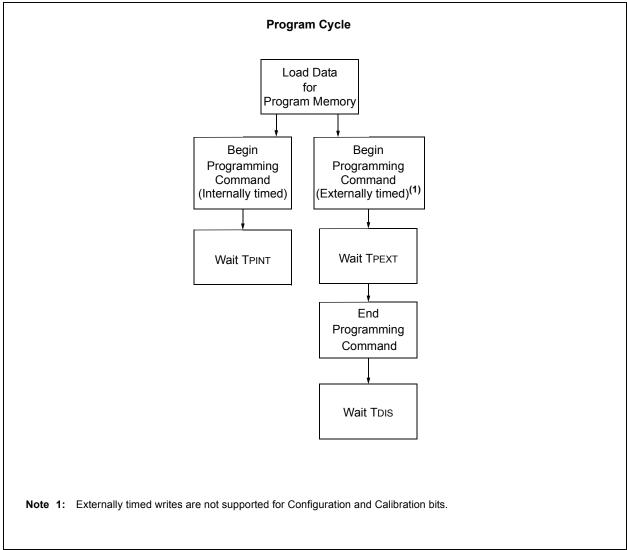
The data latches are aligned with the LSbs of the address. The PC's address at the time the Begin Externally Timed Programming or Begin Internally Timed Programming command is given will determine which location(s) in memory are written. Writes cannot cross the physical boundary. For example, with the PIC16F1527, attempting to write from address 0002h-0009h will result in data being written to 0008h-000Fh.

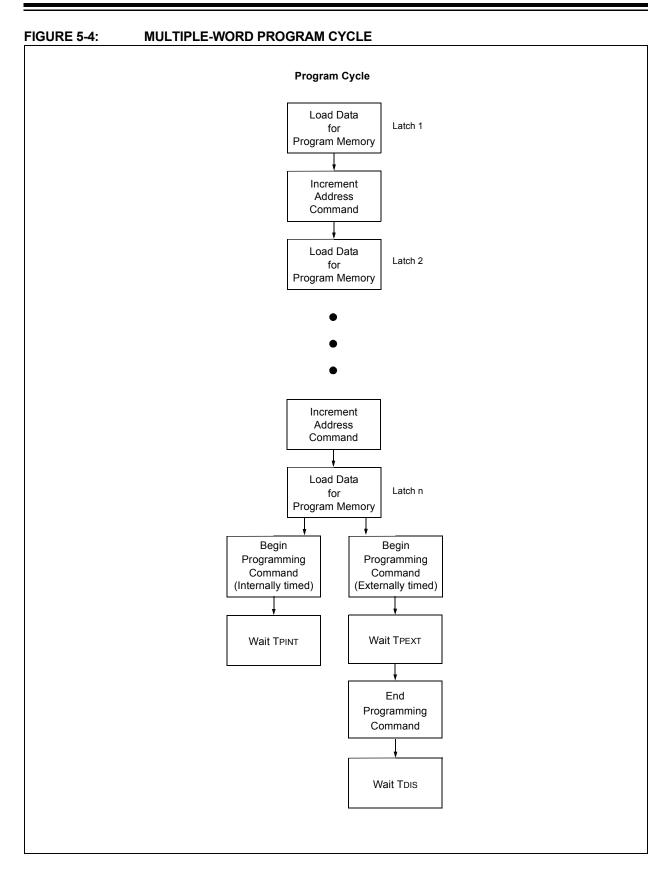
If more than the maximum number of data latches are written without a Begin Externally Timed Programming or Begin Internally Timed Programming command, the data in the data latches will be overwritten. The following figures show the recommended flowcharts for programming.

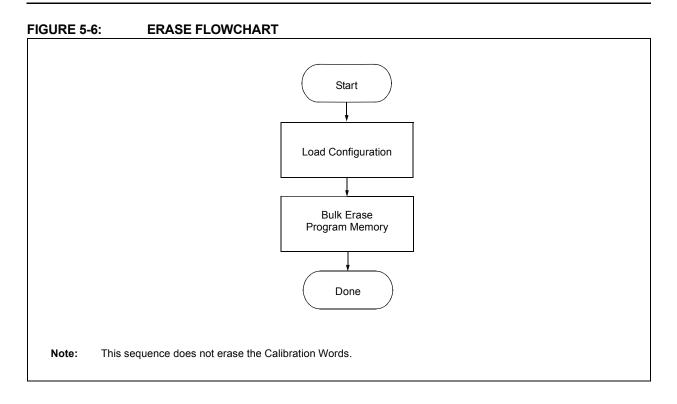




ONE-WORD PROGRAM CYCLE







7.3 Checksum Computation

The checksum is calculated by two different methods dependent on the setting of the CP Configuration bit.

MASK VALUES						
Device	Config. Word 1 Mask	Config. Word 2 Mask				
PIC16F1512	3EFFh	3E13h				
PIC16F1513	3EFFh	3E13h				
PIC16F1516	3EFFh	3E13h				
PIC16F1517	3EFFh	3E13h				
PIC16F1518	3EFFh	3E13h				
PIC16F1519	3EFFh	3E13h				
PIC16LF1512	3EFFh	3E03h				
PIC16LF1513	3EFFh	3E03h				
PIC16LF1516	3EFFh	3E03h				
PIC16LF1517	3EFFh	3E03h				
PIC16LF1518	3EFFh	3E03h				
PIC16LF1519	3EFFh	3E03h				
PIC16F1526	3EFFh	3E13h				
PIC16F1527	3EFFh	3E13h				
PIC16LF1526	3EFFh	3E03h				
PIC16LF1527	3EFFh	3E03h				

TABLE 7-1: CONFIGURATION WORD MASK VALUES

7.3.1 PROGRAM CODE PROTECTION DISABLED

With the program code protection disabled, the checksum is computed by reading the contents of the PIC16(L)F151X/152X program memory locations and adding up the program memory data starting at address 0000h, up to the maximum user addressable location. Any Carry bit exceeding 16 bits are ignored. Additionally, the relevant bits of the Configuration Words are added to the checksum. All unimplemented Configuration bits are masked to '0'.

7.3.2 PROGRAM CODE PROTECTION ENABLED

With the program code protection enabled, the checksum is computed in the following manner: The Least Significant nibble of each user ID is used to create a 16-bit value. The masked value of user ID location 8000h is the Most Significant nibble. This sum of user IDs is summed with the Configuration Words (all unimplemented Configuration bits are masked to '0').

EXAMPLE 7-3: CHECKSUM COMPUTED WITH PROGRAM CODE PROTECTION ENABLED PIC16F1527, BLANK DEVICE

PIC16F1	527 Configuration Word	(2) 3F7Fh			
	Configuration Word	mask ⁽³⁾ 3EFFh			
	Configuration Word 2	(2) 3FFFh			
	Configuration Word 2	mask ⁽³⁾ 3E13h			
	User ID (8000h) ⁽¹⁾	0006h			
	User ID (8001h) ⁽¹⁾	0007h			
	User ID (8002h) ⁽¹⁾	0001h			
	User ID (8003h) ⁽¹⁾	0002h			
	Sum of User IDs ⁽⁴⁾	= (0006h and 000Fh) << 12 + (0007h and 000Fh) << 8 +			
	(0001h and 000Fh) << 4 + (0002h and 000Fh)				
	= 6000h + 0700h + 0010h + 0002h				
		= 6712h			
	Checksum	= (3F7Fh and 3EFFh) + (3FFFh and 3E13h) + Sum of User IDs			
		= 3E7Fh +3713h + 6712h			
		= DCA4h			
Note 1:	: User ID values in this example are random values.				
2:	Configuration Word 1 and 2 = all bits are '1' except the code-protect enable bit.				
3:	Configuration Word 1 and bits which read '0'.	Mask = all Configuration Word bits are set to '1', except for unimplemented			
4:					

 <= shift left, thus the LSb of the first user ID value is the MSb of the sum of user IDs and so on, unti the LSb of the last user ID value becomes the LSb of the sum of user IDs.

EXAMPLE 7-4: CHECKSUM COMPUTED WITH PROGRAM CODE PROTECTION ENABLED PIC16LF1527, 00AAh AT FIRST AND LAST ADDRESS

	· · · · ·				
PIC16LF	1527 Configuration Word 1 ⁽²⁾	3F7Fh			
	Configuration Word 1 mask ⁽³⁾	3EFFh			
	Configuration Word 2 ⁽²⁾	3FFFh			
	Configuration Word 2 mask ^{(3), (5)}) 3E03h			
	User ID (8000h) ⁽¹⁾	000Eh			
	User ID (8001h) ⁽¹⁾	0008h			
	User ID (8002h) ⁽¹⁾	0005h			
	User ID (8003h) ⁽¹⁾	0008h			
	Sum of User IDs ⁽⁴⁾ = (000Eh a	and 000Fh) << 12 + (0008h and 000Fh) << 8 +			
	(0005h a	and 000Fh) << 4 + (0008h and 000Fh)			
	= E000h +	0800h + 0050h + 0008h			
= E858h					
	Checksum = (3F7Fh a	nd 3EFFh) + (3FFFh and 3E03h) + Sum of User IDs			
	= 3E7Fh +3	3E03h + E858h			
	= 64DAh				
Note 1:	User ID values in this example are randor	m values			
2:	Configuration Word 1 and 2 = all bits are				
3:	•				
 << = shift left, thus the LSb of the first user ID value is the MSb of the sum of user IDs and so on, unt the LSb of the last user ID value becomes the LSb of the sum of user IDs. 					
5:	On the PIC16LF1527 device, the \overline{VCAPE} unimplemented bits are '0'.	\overline{N} bit is not implemented in Configuration Word 2; thus, all			

8.0 ELECTRICAL SPECIFICATIONS

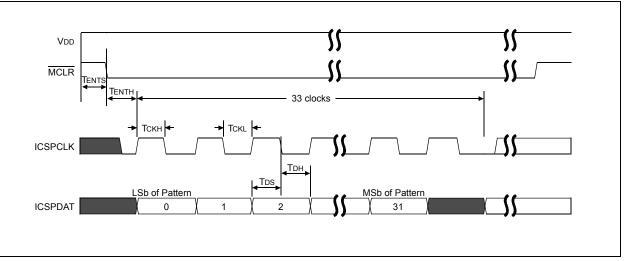
Refer to device specific data sheet for absolute maximum ratings.

TABLE 8-1: AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY MODE

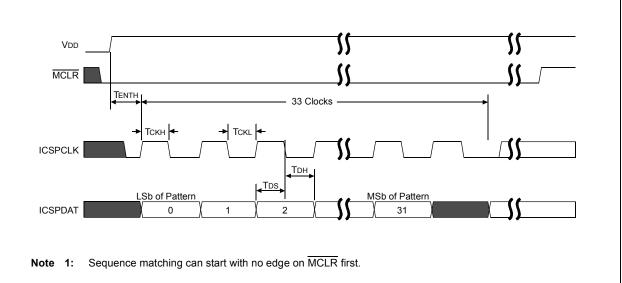
AC/DC CHARACTERISTICS			Standard O Production		J Conditions 25°C	;	
Sym.	Characteristics	Min.	Тур.	Max.	Units	Conditions/Comments	
		Supply Volt	ages and C	urrents			
Vdd	Supply Voltage	PIC16F151X PIC16F152X	2.3	_	5.5	V	
	(VDDMIN, VDDMAX)	PIC16LF151X PIC16LF152X	1.8	—	3.6	V	
VPEW	Read/Write and Row Erase opera	itions	VDDMIN		VDDMAX	V	
VPBE	Bulk Erase operations		2.7	_	VDDMAX	V	
Iddi	Current on VDD, Idle		—	—	1.0	mA	
IDDP	Current on VDD, Programming		—	_	3.0	mA	
	VPP						
IPP	Current on MCLR/VPP		_	_	600	μA	
Vінн	High voltage on MCLR/VPP for Program/Verify mode entry		8.0	_	9.0	V	
TVHHR	MCLR rise time (VIL to VIHH) for Program/Verify mode entry		_	_	1.0	μs	
	I/O pins				•		
Viн	(ICSPCLK, ICSPDAT, MCLR/VPP) input high level		0.8 Vdd	_	_	V	
VIL	(ICSPCLK, ICSPDAT, MCLR/VPP) input low level		_	_	0.2 VDD	V	
Vон	ICSPDAT output high level		Vdd-0.7 Vdd-0.7 Vdd-0.7	_	_	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 2 mA, VDD = 1.8V
Vol	ICSPDAT output low level		_	_	Vss+0.6 Vss+0.6 Vss+0.6	V	IOH = 8 mA, VDD = 5V IOH = 6 mA, VDD = 3.3V IOH = 3 mA, VDD = 1.8V
		Programming	Mode Entry	y and Exi	t		
Tents	Programing mode entry setup tim ICSPDAT setup time before VDD		100	_	_	ns	
TENTH	Programing mode entry hold time: ICSPCLK, ICSPDAT hold time after VDD or MCLR↑		250	—	_	μs	
		Serial F	Program/Vei	rify			
TCKL	Clock Low Pulse Width		100	—	—	ns	
Тскн	Clock High Pulse Width		100		—	ns	
TDS	Data in setup time before clock↓		100	—	-	ns	
Трн	Data in hold time after clock↓		100	—	-	ns	
Тсо	Clock↑ to data out valid (during a Read Data command)		0	—	80	ns	
	Clock↓ to data low-impedance (d	,					
Tlzd	Read Data command)	-	0	—	80	ns	
THZD	Clock↓ to data high-impedance (during a Read Data command)		0	_	80	ns	
TDLY	Data input not driven to next clock input (delay required between command/data or command/ command)		1.0	_	_	μs	
TERAB	Bulk Erase cycle time		—	—	5	ms	
TERAR	Row Erase cycle time		—	—	2.5	ms	

Note 1: Externally timed writes are not supported for Configuration and Calibration bits.









NOTES: